

Dual P-Channel 2.5-V (G-S) MOSFET

PRODUCT SUMMARY

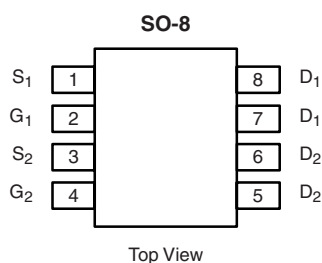
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)
- 20	0.032 at $V_{GS} = - 4.5$ V	- 6.5
	0.050 at $V_{GS} = - 2.5$ V	- 5.2

FEATURES

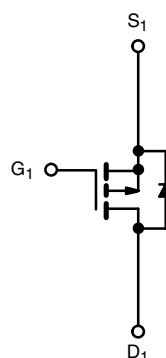
- Halogen-free According to IEC 61249-2-21 Definition
- Compliant to RoHS Directive 2002/95/EC



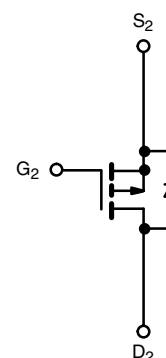
RoHS
COMPLIANT
HALOGEN
FREE
Available



Ordering Information: Si4963BDY-T1-E3 (Lead (Pb)-free)
Si4963BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)



P-Channel MOSFET



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	10 s	Steady State	Unit
Drain-Source Voltage	V_{DS}	- 20		V
Gate-Source Voltage	V_{GS}	± 12		
Continuous Drain Current ($T_J = 150$ °C) ^a	I_D	- 6.5	- 4.9	A
		- 5.2	- 3.9	
Pulsed Drain Current	I_{DM}	- 40		
Continuous Source Current (Diode Conduction) ^a	I_S	- 1.7	- 0.9	
Maximum Power Dissipation ^a	P_D	2.0	1.1	W
		1.3	0.7	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	R_{thJA}	58	62.5	°C/W
		91	110	
Maximum Junction-to-Foot (Drain)	R_{thJF}	34	40	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

For SPICE model information via the Worldwide Web: <http://www.vishay.com/www/product/spice.htm>.

SPECIFICATIONS $T_J = 25^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = -250\ \mu\text{A}$	- 0.6		- 1.4	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\ \text{V}$, $V_{GS} = \pm 12\ \text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20\ \text{V}$, $V_{GS} = 0\ \text{V}$			- 1	μA
		$V_{DS} = -20\ \text{V}$, $V_{GS} = 0\ \text{V}$, $T_J = 55^\circ\text{C}$			- 5	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \leq -5\ \text{V}$, $V_{GS} = -4.5\ \text{V}$	- 20			A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = -4.5\ \text{V}$, $I_D = -6.5\ \text{A}$		0.025	0.032	Ω
		$V_{GS} = -2.5\ \text{V}$, $I_D = -2\ \text{A}$		0.040	0.050	
Forward Transconductance ^a	g_{fs}	$V_{DS} = -10\ \text{V}$, $I_D = -6.5\ \text{A}$		18		S
Diode Forward Voltage ^a	V_{SD}	$I_S = -1.7\ \text{A}$, $V_{GS} = 0\ \text{V}$		- 0.75	- 1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = -10\ \text{V}$, $V_{GS} = -4.5\ \text{V}$, $I_D = -6.5\ \text{A}$		14	21	nC
Gate-Source Charge	Q_{gs}			2.6		
Gate-Drain Charge	Q_{gd}			4.6		
Gate Resistance	R_g	$f = 1\ \text{MHz}$		8.3		Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10\ \text{V}$, $R_L = 10\ \Omega$ $I_D \cong -1\ \text{A}$, $V_{GEN} = -4.5\ \text{V}$, $R_g = 6\ \Omega$		30	45	ns
Rise Time	t_r			40	60	
Turn-Off Delay Time	$t_{d(off)}$			80	120	
Fall Time	t_f			55	85	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = -1.7\ \text{A}$, $di/dt = 100\ \text{A}/\mu\text{s}$		40	80	

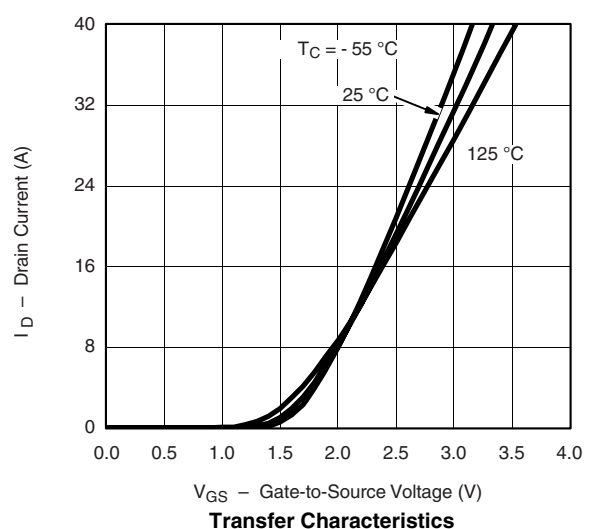
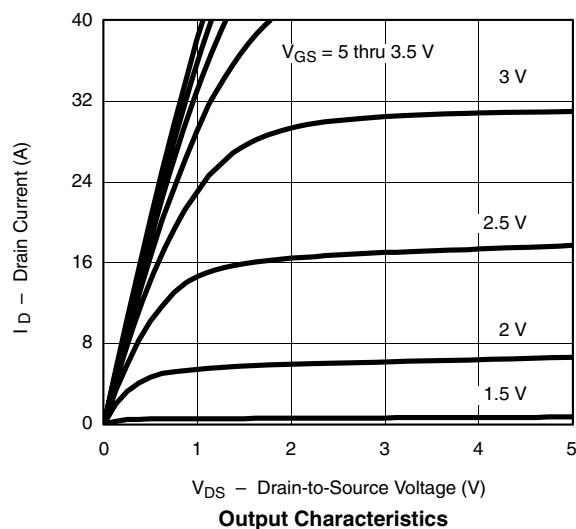
Notes:

a. Pulse test; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.

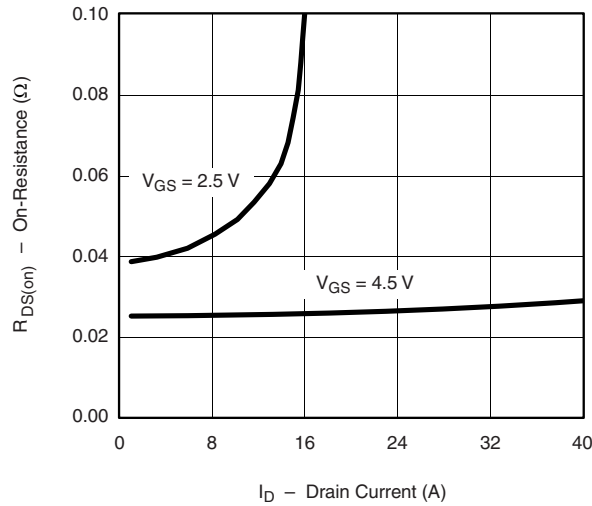
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

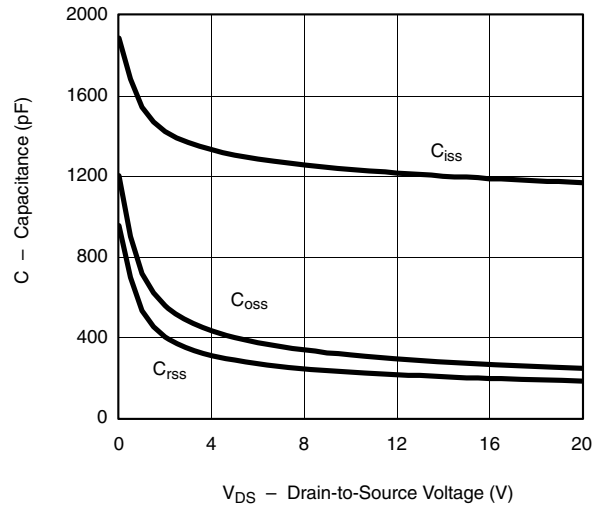
TYPICAL CHARACTERISTICS 25°C unless otherwise noted



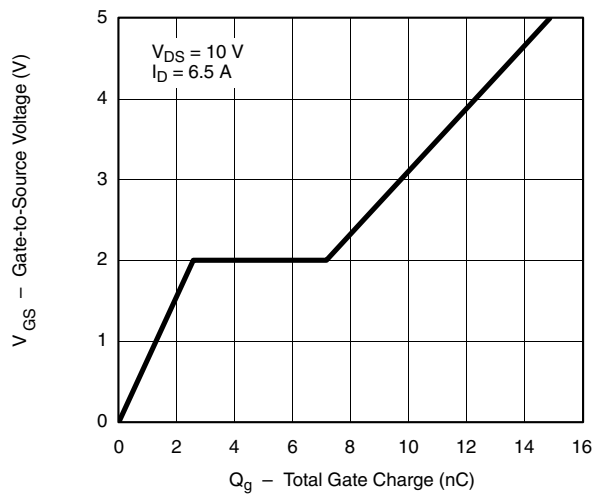
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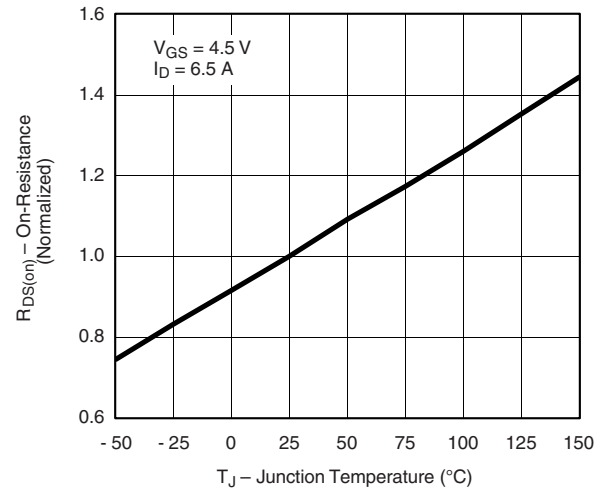
On-Resistance vs. Drain Current



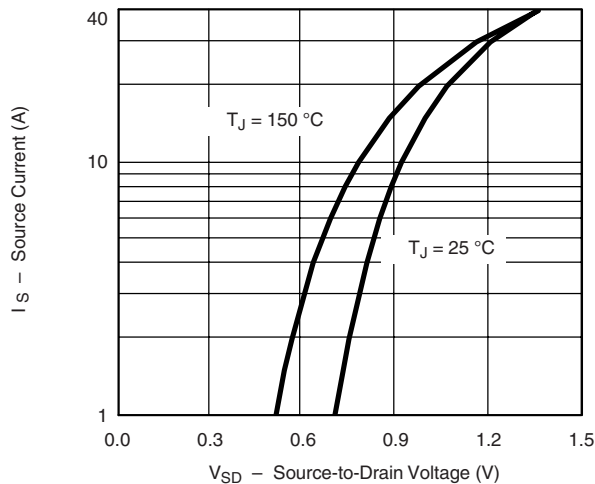
Capacitance



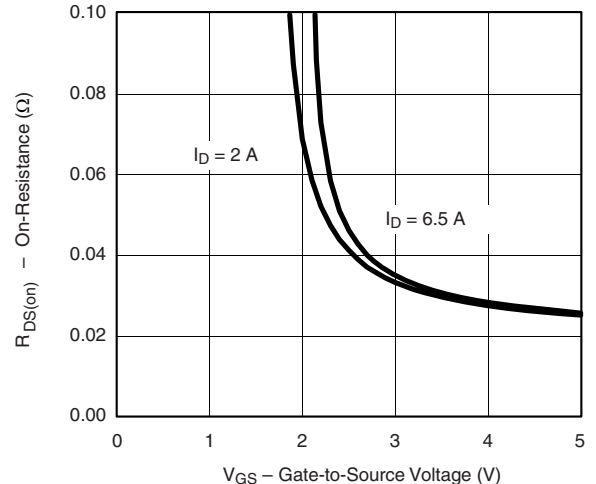
Gate Charge



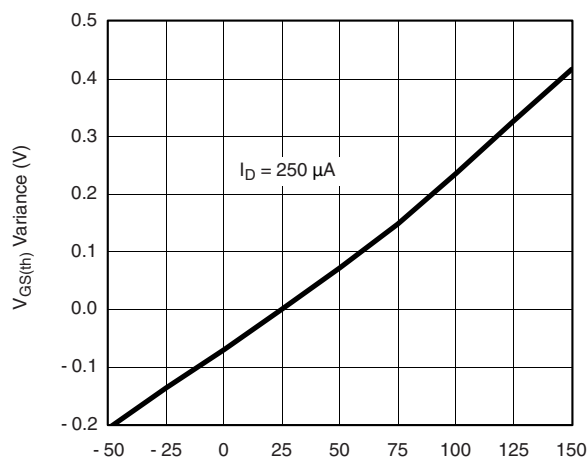
On-Resistance vs. Junction Temperature



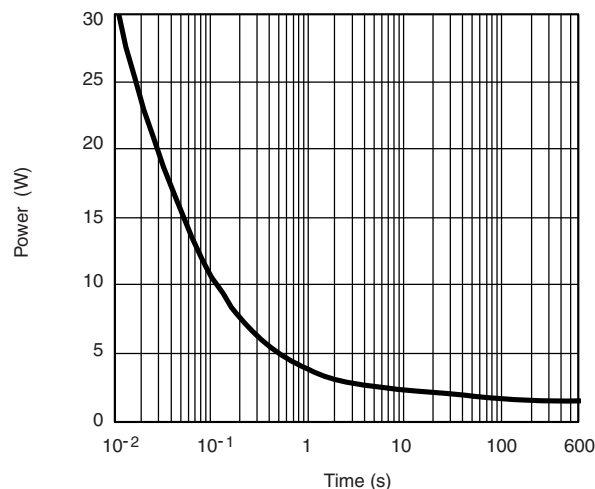
Source-Drain Diode Forward Voltage



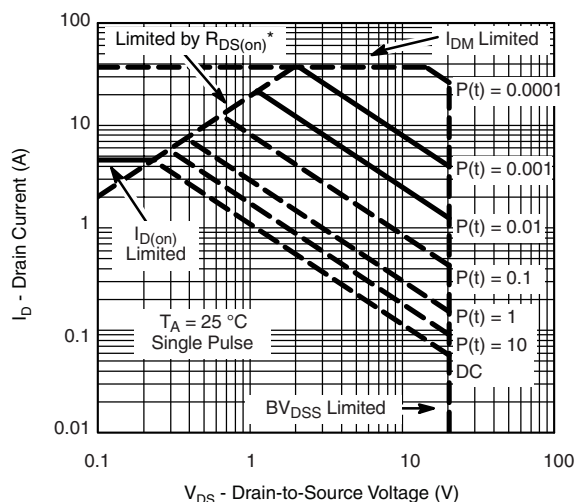
On-Resistance vs. Gate-to-Source Voltage

TYPICAL CHARACTERISTICS 25 °C unless otherwise noted T_J - Temperature (°C)

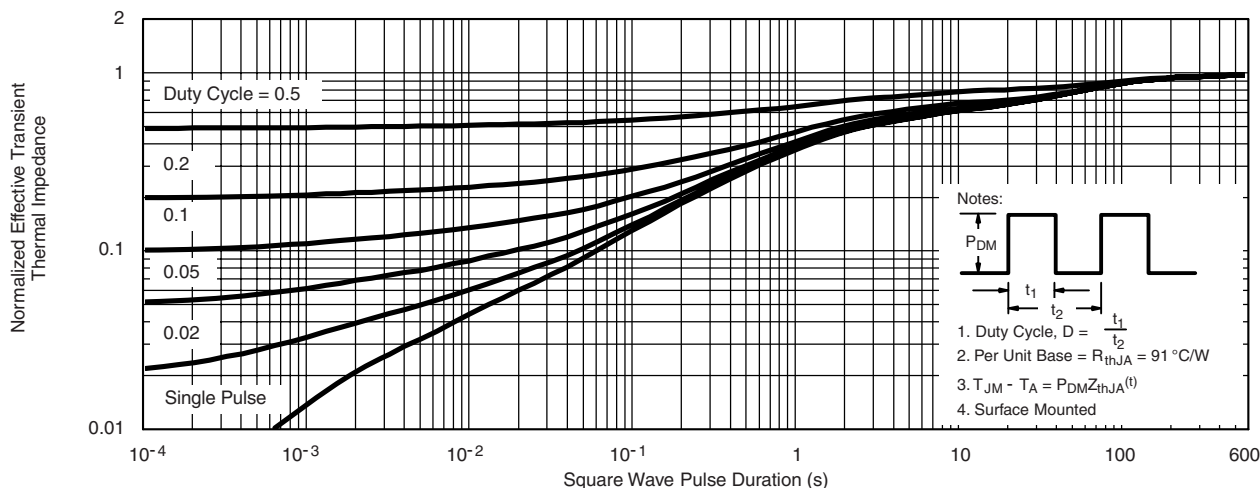
Threshold Voltage



Single Pulse Power

 V_{DS} - Drain-to-Source Voltage (V)* $V_{DS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

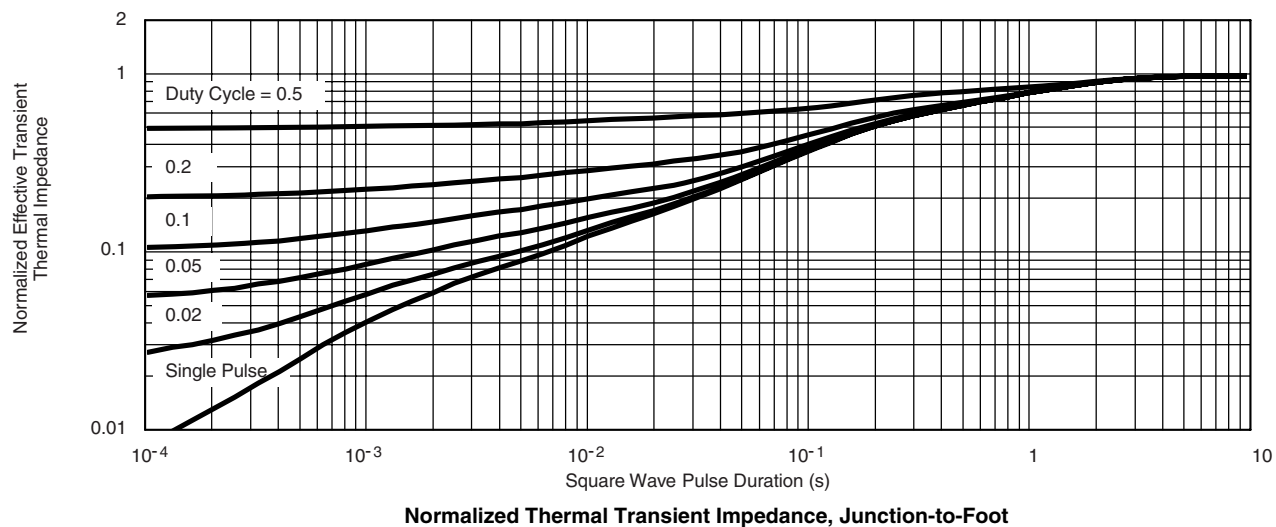
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?72753.



SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012



DIM	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	1.35	1.75	0.053	0.069
A ₁	0.10	0.20	0.004	0.008
B	0.35	0.51	0.014	0.020
C	0.19	0.25	0.0075	0.010
D	4.80	5.00	0.189	0.196
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.020
L	0.50	0.93	0.020	0.037
q	0°	8°	0°	8°
S	0.44	0.64	0.018	0.026
ECN: C-06527-Rev. I, 11-Sep-06				
DWG: 5498				

RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads
Dimensions in Inches/(mm)

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